

Dual P-Ch 20V Fast Switching MOSFETs

Features:

- ★ Green Device Available
- ★ Super Low Gate Charge
- ★ Excellent CdV/dt effect decline
- ★ Advanced high cell density Trench technology



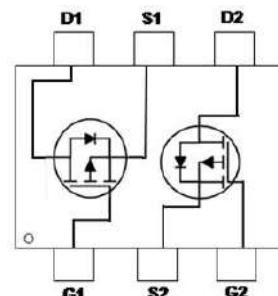
Description:

The KTQ4953 is the high cell density trenched P-ch MOSFETs, which provide excellent RDSON and gate charge for most of the small power switching and load switch applications.

The KTQ4953 meet the RoHS and Green Product requirement with full function reliability approved.

BVDSS	RDS(on)	ID
-20V	100mΩ	-3.0A

TSOP6 Pin Configuration



Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V _{DS}	Drain-Source Voltage	-20	V
V _{GS}	Gate-Source Voltage	±12	V
I _D @T _A =25°C	Continuous Drain Current, V _{GS} @ -4.5V ¹	-3	A
I _D @T _A =70°C	Continuous Drain Current, V _{GS} @ -4.5V ¹	-2	A
I _{DM}	Pulsed Drain Current ²	-10	A
P _D @T _A =25°C	Total Power Dissipation ³	1.25	W
T _{STG}	Storage Temperature Range	-55 to 150	°C
T _J	Operating Junction Temperature Range	-55 to 150	°C

Symbol	Parameter	Typ.	Max.	Unit
R _{θJA}	Thermal Resistance Junction-ambient ¹	---	100	°C/W
R _{θJA}	Thermal Resistance Junction-ambient ^{1,t≤10s}	---	70	°C/W

Electrical Characteristics ($T_J=25^{\circ}\text{C}$, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$\text{V}_{\text{GS}}=0\text{V}$, $\text{I}_D=-250\mu\text{A}$	-20	---	---	V
$\text{R}_{\text{DS}(\text{ON})}$	Static Drain-Source On-Resistance ²	$\text{V}_{\text{GS}}=-4.5\text{V}$, $\text{I}_D=-3\text{A}$	---	85	100	$\text{m}\Omega$
		$\text{V}_{\text{GS}}=-2.5\text{V}$, $\text{I}_D=-2\text{A}$	---	120	140	
$\text{V}_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$\text{V}_{\text{GS}}=\text{V}_{\text{DS}}$, $\text{I}_D=-250\mu\text{A}$	-0.4	-0.6	-1.2	V
I_{DSS}	Drain-Source Leakage Current	$\text{V}_{\text{DS}}=-16\text{V}$, $\text{V}_{\text{GS}}=0\text{V}$, $T_J=25^{\circ}\text{C}$	---	---	-1	uA
		$\text{V}_{\text{DS}}=-16\text{V}$, $\text{V}_{\text{GS}}=0\text{V}$, $T_J=55^{\circ}\text{C}$	---	---	-5	
I_{GSS}	Gate-Source Leakage Current	$\text{V}_{\text{GS}}=\pm 12\text{V}$, $\text{V}_{\text{DS}}=0\text{V}$	---	---	± 100	nA
g_{fs}	Forward Transconductance	$\text{V}_{\text{DS}}=-5\text{V}$, $\text{I}_D=-3\text{A}$	---	12.2	---	S
Q_{g}	Total Gate Charge (-4.5V)	$\text{V}_{\text{DS}}=-15\text{V}$, $\text{V}_{\text{GS}}=-4.5\text{V}$, $\text{I}_D=-3\text{A}$	---	10.1	---	nC
Q_{gs}	Gate-Source Charge		---	1.21	---	
Q_{gd}	Gate-Drain Charge		---	2.46	---	
$\text{T}_{\text{d}(\text{on})}$	Turn-On Delay Time	$\text{V}_{\text{DD}}=-10\text{V}$, $\text{V}_{\text{GS}}=-4.5\text{V}$, $\text{R}_G=3.3\Omega$ $\text{I}_D=-3\text{A}$	---	5.6	---	ns
T_r	Rise Time		---	32.2	---	
$\text{T}_{\text{d}(\text{off})}$	Turn-Off Delay Time		---	45.6	---	
T_f	Fall Time		---	29.2	---	
C_{iss}	Input Capacitance	$\text{V}_{\text{DS}}=-15\text{V}$, $\text{V}_{\text{GS}}=0\text{V}$, $f=1\text{MHz}$	---	677	---	pF
C_{oss}	Output Capacitance		---	82	---	
C_{rss}	Reverse Transfer Capacitance		---	73	---	

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_{s}	Continuous Source Current ^{1,4}	$\text{V}_{\text{G}}=\text{V}_{\text{D}}=0\text{V}$, Force Current	---	---	-2	A
V_{SD}	Diode Forward Voltage ²	$\text{V}_{\text{GS}}=0\text{V}$, $\text{I}_{\text{s}}=-1\text{A}$, $T_J=25^{\circ}\text{C}$	---	---	-1	V

Note :

- 1.The data tested by surface mounted on a 1 inch²FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$
- 3.The power dissipation is limited by 150°C junction temperature
- 4.The data is theoretically the same as I_{D} and I_{DM} , in real applications , should be limited by total power dissipation.

Typical Characteristics

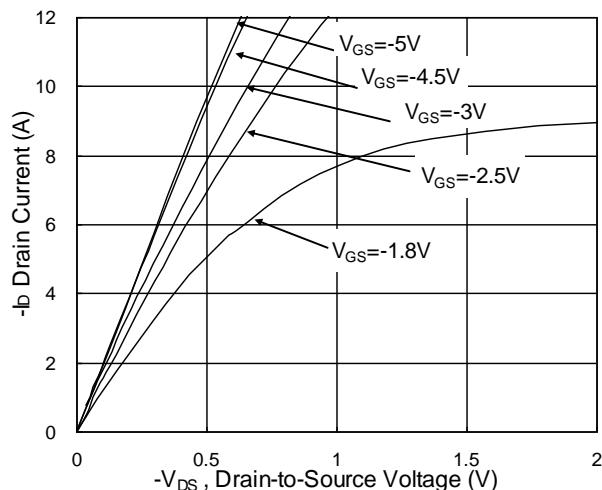


Fig.1 Typical Output Characteristics

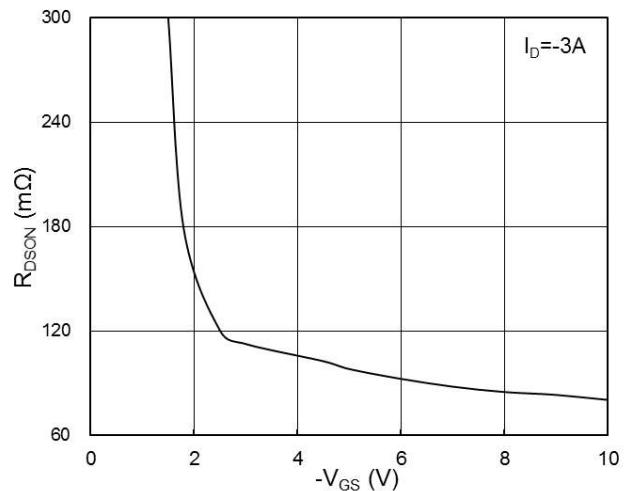


Fig.2 On-Resistance vs G-S Voltage

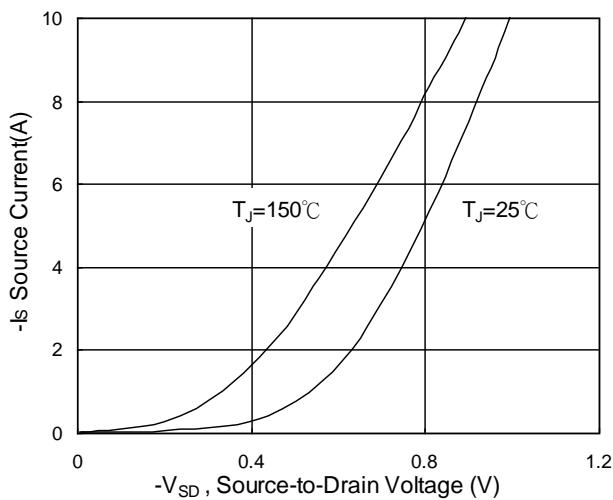


Fig.3 Source Drain Forward Characteristics

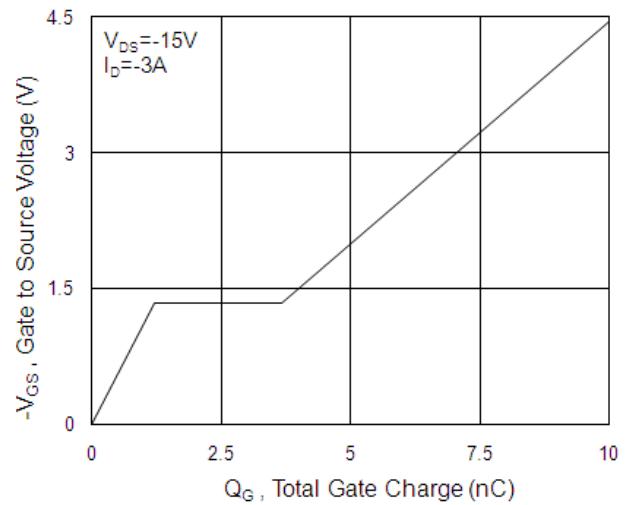


Fig.4 Gate-Charge Characteristics

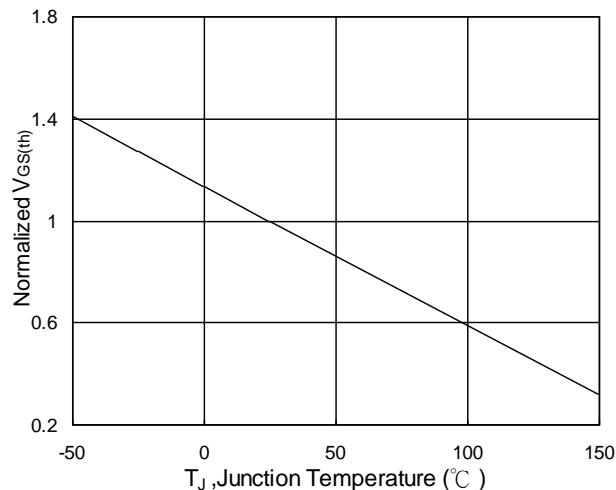


Fig.5 Normalized $V_{GS(th)}$ vs T_J

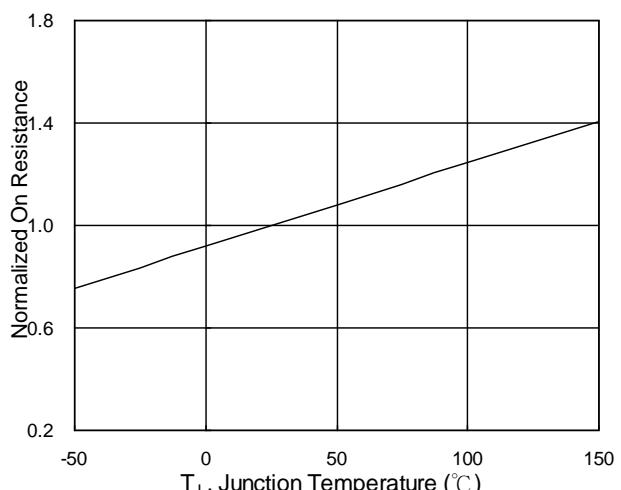


Fig.6 Normalized $R_{DS(on)}$ vs T_J

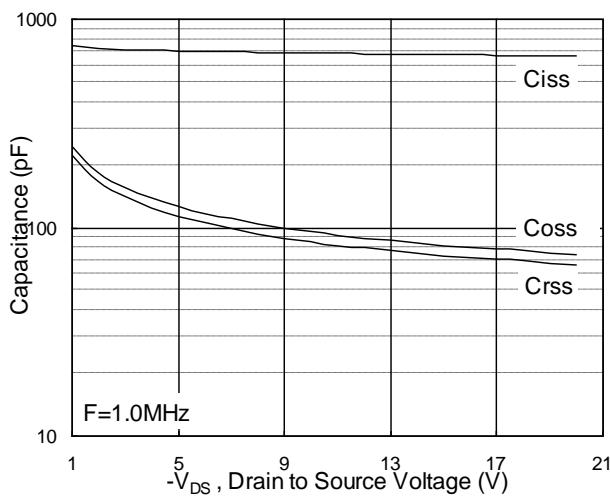


Fig.7 Capacitance

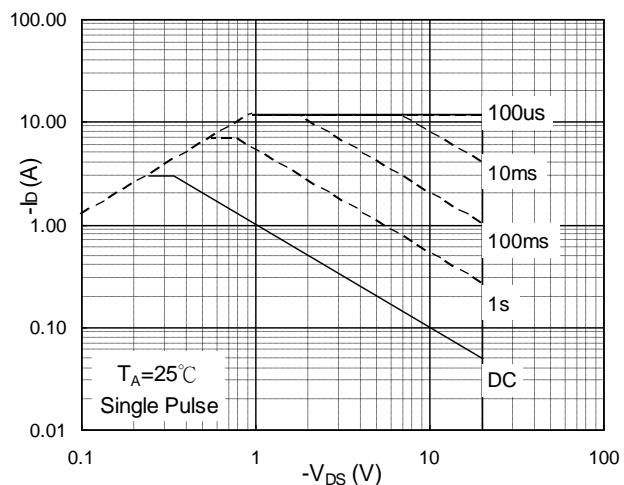


Fig.8 Safe Operating Area

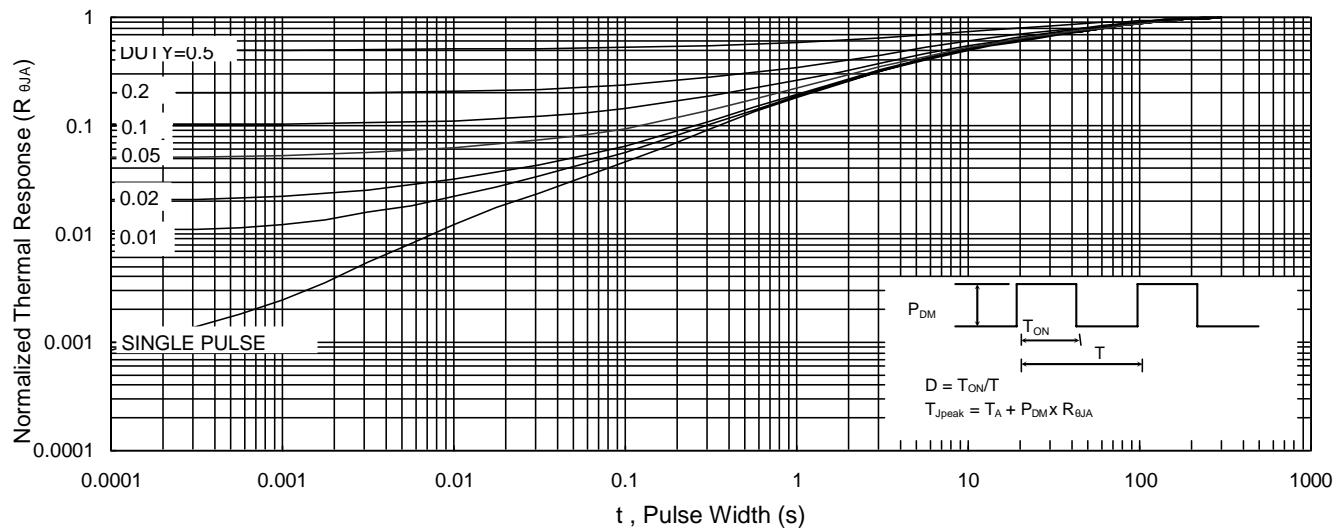


Fig.9 Normalized Maximum Transient Thermal Impedance

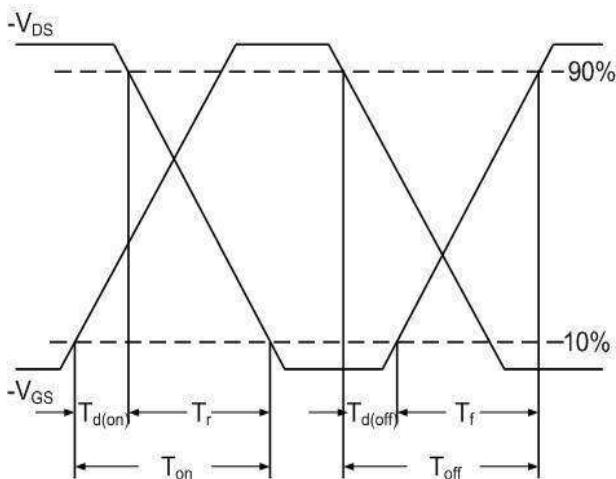


Fig.10 Switching Time Waveform

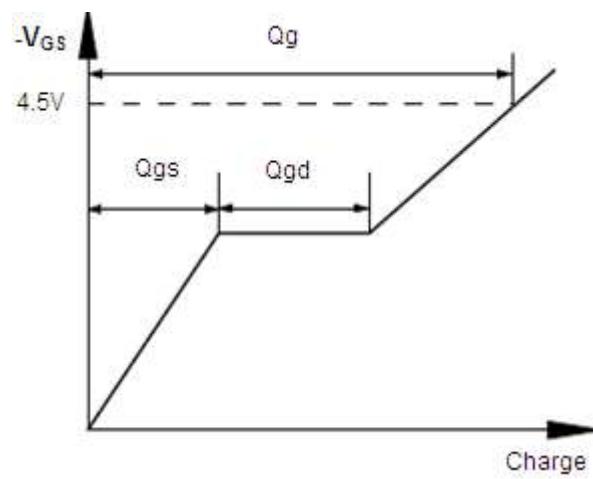
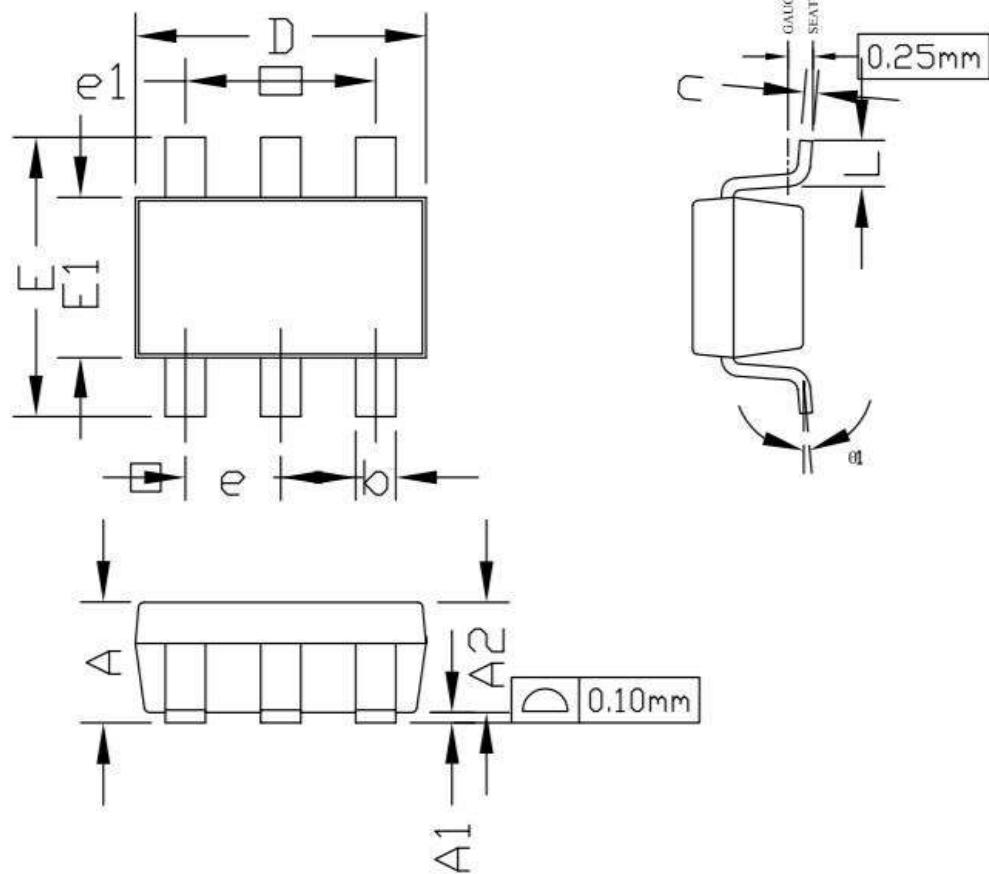
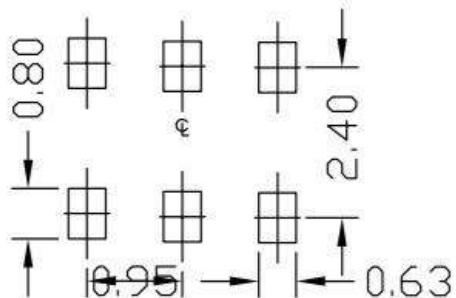


Fig.11 Gate Charge Waveform

TSOP6 Package Outline Dimensions



RECOMMENDED LAND PATTERN



UNIT: mm

SYMBOLS	DIMENSIONS IN MILLIMETERS			DIMENSIONS IN INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.80	—	1.25	0.031	—	0.049
A1	0.00	—	0.15	0.000	—	0.006
A2	0.70	1.10	1.20	0.028	0.043	0.047
b	0.30	0.40	0.50	0.012	0.016	0.020
c	0.08	0.13	0.20	0.003	0.005	0.008
D	2.70	2.90	3.10	0.106	0.114	0.122
E	2.50	2.80	3.10	0.098	0.110	0.122
E1	1.50	1.60	1.70	0.059	0.063	0.067
e	0.95 BSC.			0.037BSC.		
e1	1.90 BSC.			0.075 BSC.		
L	0.30	—	0.60	0.012	—	0.024
theta1	0°	—	8°	0°	—	8°